EMVCo Security Evaluation

Development / Production Site Attestation Letter

Please accept this document as confirmation of the EMVCo Security Evaluation Process.

Reference: SALN0042

Company: Goldpac Limited

Site Name: Goldpac R&D Center – Development

Site Address: 8th Floor, Block B Hainan Airline Building
No. (B) 2 of North Road, 3rd East Ring Road, Chaoyang District
Beijing, 100027
People's Republic of China

Type: Development

Date Issued: 20 Nov 2020

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Security Laboratory: Applus

The EMVCo Security Evaluation Process is intended to provide with valuable and practical information relating to the general security performance characteristics and the suitability of use for smart card related products and IC chip-based tokens. The EMVCo Security Evaluation Process is designed to ensure a robust security foundation for these products at the product family and component level. The full terms and conditions upon which EMVCo Attestation Letters are issued by EMVCo are contained in the EMVCo Security Evaluation Process Document and the EMVCo Security Evaluation Certification Contract.